



Low Profile (25°) DIMM Socket

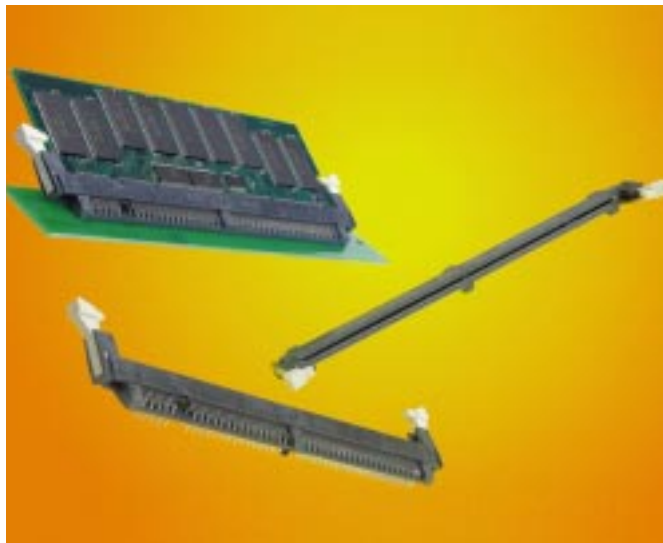
(1.27mm Pitch, Multi-Key)

Introduction

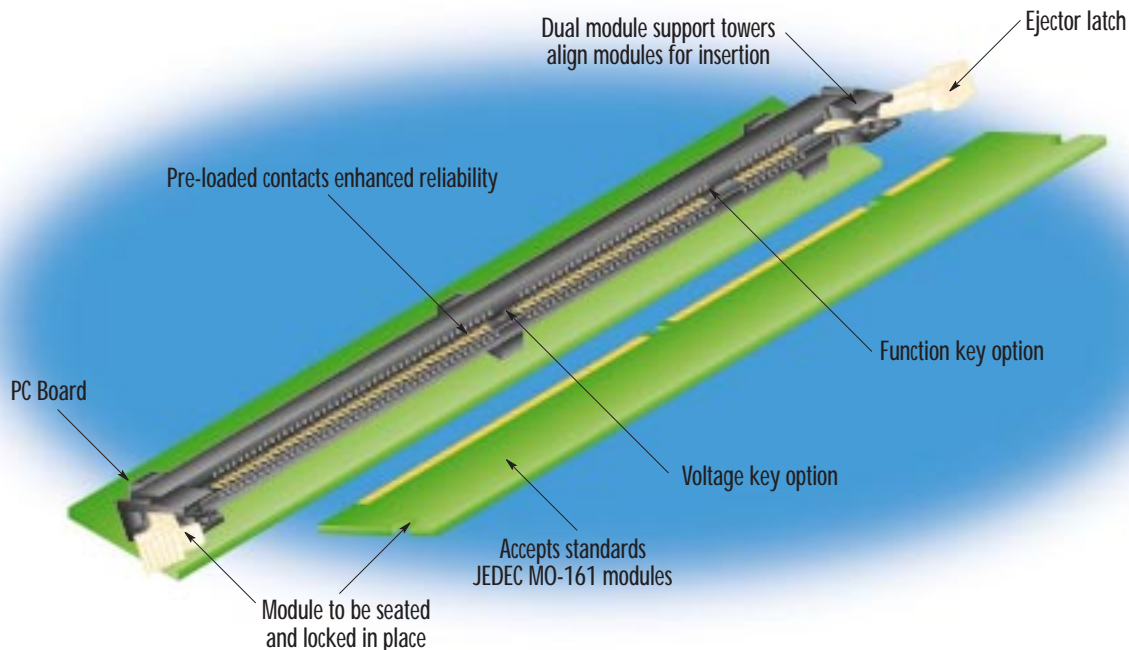
Dual In-line Memory Modules (DIMMs) are widely adopted by computer industries as DIMMs offer the ability to easily upgrade memory using industry standard modules.

The continuous increase in systems complexities have resulted in chassis height and PCI Card spacing constraints. Molex now offers Through-Hole DIMM in 25 degree angle to allow customers to better utilize their available space. The Angled DIMM socket is an extension of the very popular Molex vertical DIMM socket.

Molex Angled DIMM sockets accept modules conforming to specification established by JEDEC. For more information, please contact your nearest Molex sales office or visit our worldwide website.



Features & Benefits



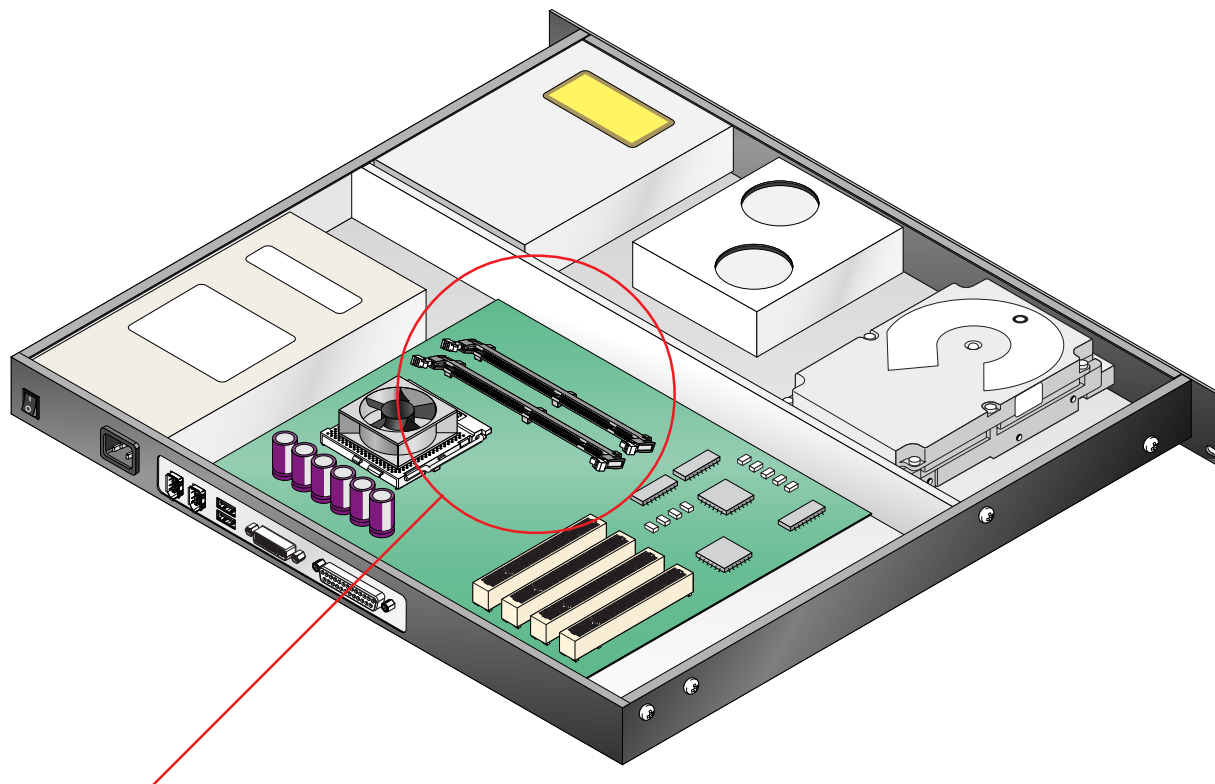
Ordering Information and Dimensions

Circuits	Order No.		Function Key	Voltage Key	Solder Tail Length	Recommended PCB Thickness
	15μ" Select Gold	30μ" Select Gold				
168	87587-0048	87587-0148	Left	Center (3.3V)	2.79 (.110)	2.19 (.086) max.
	87587-0049	87587-0149	Center	Center (3.3V)	2.79 (.110)	
	87587-0050	87587-0150	Right	Center (3.3V)	2.79 (.110)	
	87587-0057	87587-0157	Left	Center (3.3V)	3.18 (.125)	2.58 (.101) max.
	87587-0058	87587-0158	Center	Center (3.3V)	3.18 (.125)	
	87587-0059	87587-0159	Right	Center (3.3V)	3.18 (.125)	



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Typical Application



25 degree DIMM application for low profile 1U server



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